

FEATURES**General**

- Low power MIPI/DSI receiver
- Low power HDMI/DVI transmitter ideal for portable applications
- CEC controller and expanded message buffer (3 messages) reduces system overhead
- Incorporates HDMI v.1.3 (x.v.Color™) technology
- Compatible with DVI v.1.0
- Optional embedded HDCP keys to support HDCP 1.3
- 1.8 V, 1.2 V (optional), and 3.3 V supplies for ultralow operating power
- Audio inputs accept logic levels from 1.8 V to 3.3 V

MIPI/DSI receiver

- 2-, 3-, or 4-lane DSI receiver
- Supports up to 800 Mbps per lane
- Compatible with DPHY V.0.90 and DSI V.1.02
- Supports inputs of
 - 16-bit RGB 4:4:4
 - 24-bit RGB 4:4:4
 - 30-bit RGB 4:4:4

HDMI (TMDS) video out

- 80 MHz operation supports all video and graphics resolutions from 480i to 1080p at 30 Hz
- Programmable 2-way color space converter
- Output supports
 - 36-, 30-, or 24-bit RGB 4:4:4
 - 36-, 30-, or 24-bit YCbCr 4:4:4
- Automatic input video format timing detection (CEA-861E)

Digital audio

- Supports standard S/PDIF for stereo LPCM or compressed audio up to 192 kHz
- 2-channel uncompressed LPCM I²S audio up to 192 kHz

Special features for easy system design

- On-chip MPU with I²C master to perform EDID reading and HDCP operations; reports HDMI events through interrupts and registers
- 5 V tolerant I²C and HPD I/Os, no extra device needed
- No audio master clock needed for supporting S/PDIF and I²S

APPLICATIONS

- Mobile systems
- Cellular handsets
- Digital video cameras
- Digital still cameras
- Personal media players
- Gaming

GENERAL DESCRIPTION

The [ADV7533](#) is a multifunction video interface chip. The [ADV7533](#) provides a mobile industry processor interface/display serial interface (MIPI®/DSI) input port, a high definition multimedia interface (HDMI®) data output in a 49-ball wafer level chip scale package (WLCSP). The display serial interface (DSI) input provides up to four lanes of MIPI/DSI data, each running up to 800 Mbps. The DSI Rx implements DSI video mode operation only. The HDMI Tx supports video resolutions using pixel clocks of up to 80 MHz.

With the optional inclusion of embedded HDCP keys, the [ADV7533](#) allows the secure transmission of protected content, as specified by the HDCP 1.3 protocol.

The [ADV7533](#) supports x.v.Color™ (gamut metadata) for a wider color gamut.

The [ADV7533](#) supports both S/PDIF and 2-channel I²S audio. Its high fidelity 2-channel I²S can transmit stereo up to a 192 kHz sampling rate. The S/PDIF can carry stereo LPCM audio or compressed audio, including Dolby® Digital and DTS®.

The [ADV7533](#) helps to reduce system design complexity and cost by incorporating such features as an I²C master for EDID reading and 5 V tolerance on the I²C and Hot Plug™ detect pins.

Fabricated in an advanced CMOS process, the [ADV7533](#) is available in a space saving, 49-ball, WLCSP surface mount package. This package is RoHS compliant and specified to operate from -10°C to +85°C.

Rev. A

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REVISION HISTORY

8/12—Rev. 0 to Rev. A

Changed Storage Temperature from -65°C to $+150^{\circ}\text{C}$ to -40°C to $+85^{\circ}\text{C}$ 8

7/11—Revision 0: Initial Version

FUNCTIONAL BLOCK DIAGRAM

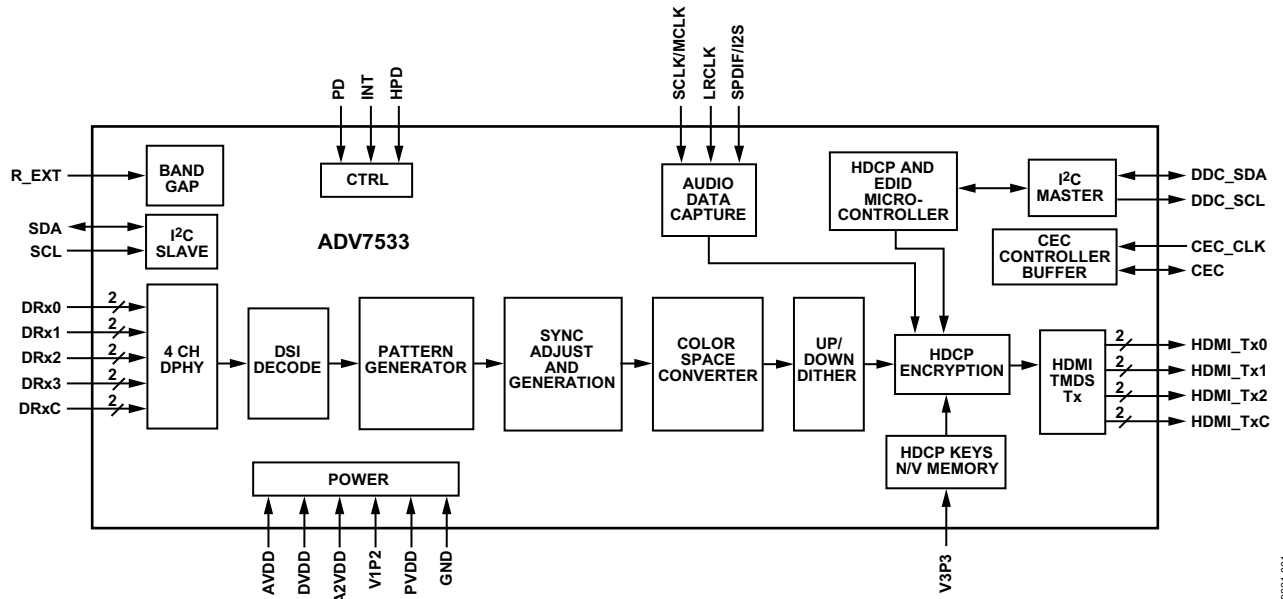


Figure 1.

08821-001

SPECIFICATIONS

Table 1. Electrical Specifications

Parameter	Conditions	Temp	Test Level ¹	ADV7533BCBZ			Unit
				Min	Typ	Max	
DIGITAL INPUTS							
Data Inputs—Audio, CEC_CLK							
Input Voltage, High (V _{IH})		Full	VI	1.4		3.5	V
Input Voltage, Low (V _{IL})		Full	VI	-0.3		+0.7	V
Input Capacitance		25°C	VIII		1.0	1.5	pF
I²C Lines (SDA, SCL)							
Input Voltage, High (V _{IH})		Full	VI	1.3		5.5	V
Input Voltage, Low (V _{IL})		Full	VI	-0.3		+0.6	V
I²C Lines (DDCSDA, DDSCSL)							
Input Voltage, High (V _{IH})	Default values	Full	VI	1.3		5.5	V
Input Voltage, Low (V _{IL})		Full	VI	-0.3		+0.6	V
Input Voltage, High (V _{IH})	Programmable optional values	Full	IV	3.5		5.5	V
Input Voltage, Low (V _{IL})		Full	IV	-0.5		+1.2	V
CEC							
Input Voltage, High (V _{IH})		Full	VI	2.0			V
Input Voltage, Low (V _{IL})		Full	VI			0.6	V
Output Voltage, High (V _{OH})		Full	VI	2.5		3.63	V
Output Voltage, Low (V _{OL})		Full	VI	-0.3		+0.6	V
HPD							
Input Voltage, High (V _{IH})		Full	VI	1.3		5.5	V
Input Voltage, Low (V _{IL})		Full	VI	-0.3		+0.6	V
DIGITAL OUTPUTS—INT							
Output Voltage, Low (V _{OL})	Load = 5 pF	Full	VI			0.4	V
THERMAL CHARACTERISTICS							
Thermal Resistance							
θ _{JC} Junction-to-Case		Full	V		20		°C/W
θ _{JA} Junction-to-Ambient		Full	V		43		°C/W
Ambient Temperature		Full	V	-10	+25	+85	°C
DC SPECIFICATIONS							
Input Leakage Current, I _{IL}		25°C	VI	-1		+1	µA
POWER SUPPLY							
1.8 V Supply Voltage (DV _{DD} , AV _{DD} , A2V _{DD} , PV _{DD})		Full	IV	1.71	1.8	1.9	V
V1P2 = (1.2 V)		Full	IV	1.14	1.2	1.26	V
V1P2 = (1.8 V)		Full	IV	1.71	1.8	1.9	V
Supply Voltage Noise Limit							
DVDD —Digital I/O Pad Logic		Full	IV			64	mV rms
AVDD—HDMI Analog Core		Full	IV			64	mV rms
V1P2—HDMI/DSI Digital Core							
1.2 V		Full	IV			43	mV rms
1.8 V		Full	IV			64	mV rms
A2VDD—MIPI DPHY		Full	IV			64	mV rms
PVDD—HDMI PLL	Refer to Figure 2	Full	IV			64	mV rms
3.3 V Supply Voltage (V3P3)		Full	IV	3.15	3.30	3.45	V
3.3 V Supply Voltage Noise Limit		Full	IV			64	mV rms
Power-Down Current		25°C	VI		15		µA
Operating Current							
DVDD	I/O pads (30 bits at 720p)	Full	IV		6		mA

Parameter	Conditions	Temp	Test Level ¹	ADV7533BCBZ			Unit
				Min	Typ	Max	
AVDD	HDMI analog core (24 bits at 720p)	Full	IV		11		mA
V1P2 (1.2 V)	HDMI/DSI digital core (DSI 30 bits/HDMI 24 bits at 720p)	Full	IV		39		mA
A2VDD	MIPI DPHY (30 bits/three lanes/720p)	Full	IV		12		mA
PVDD	HDMI PLL (24 bits at 720p)	Full	IV		11		mA
V3P3—HDMI/HDCP Memory Transmitter Total Power	HDMI HDCP memory 720p, 30-bit DSI in; 720p, 36-bit HDMI out; typical random pattern with CSC enabled, HDCP enabled, audio enabled	Full	IV		0.3		mA
V1P2 = 1.2 V		Full	IV		120	154	mW
V1P2 = 1.8 V		Full	VI			204	mW
AC SPECIFICATIONS							
TMDS Output Clock Frequency		25°C	IV	20		112	MHz
TMDS Output Clock Duty Cycle		25°C	IV	48		52	%
TMDS Differential Swing		25°C	VII	800	1000	1200	mV
Differential Output Timing							
Low-to-High Transition Time		25°C	VII	75	175		ps
High-to-Low Transition Time		25°C	VII	75	175		ps
AUDIO AC TIMING²							
SCLK Duty Cycle							
When N = Even Number		Full	IV	40	50	60	%
When N = Odd Number		Full	IV	49	50	51	%
I ² S, S/PDIF Setup, t _{ASU}		Full	IV	2			ns
I ² S, S/PDIF Hold Time, t _{AHLD}		Full	IV	2			ns
LRCLK Setup Time, t _{ASU}		Full	IV	2			ns
LRCLK Hold Time, t _{AHLD}		Full	IV	2			ns
CEC							
CEC_CLK Frequency ³		Full	VIII	3	12	100	MHz
CEC_CLK Accuracy		Full	VIII	-2		+2	%
CEC_CLK Duty Cycle		Full	VIII	40		60	%
I²C INTERFACE							
SCL Clock Frequency		Full	VIII			400 ⁴	kHz
SDA Setup Time, t _{DSU}		Full	VIII	100			ns
SDA Hold Time, t _{DHO}		Full	VIII	100			ns
Setup for Start, t _{STASU}		Full	VIII	0.6			µs
Hold Time for Start, t _{STAH}		Full	VIII	0.6			µs
Setup for Stop, t _{STOSU}		Full	VIII	0.6			µs
Bus Free Between Stop and Start, t _{BUF}		Full	VIII	1.3			µs
SCL High, t _{HIGH}		Full	VIII	0.6			µs
SCL Low, t _{LOW}		Full	VIII	1.3			µs

¹ See the Explanation of Test Levels section.

² 12 MHz crystal for default register settings.

³ Only applies to S/PDIF if external MCLK is used.

⁴ I²C data rates of 100 KHz and 400 KHz are supported.

The power supply noise sensitivity of the [ADV7533](#) is frequency dependent. Therefore, the maximum noise limit for the PVDD is specified in mV rms vs. frequency (see Figure 2).

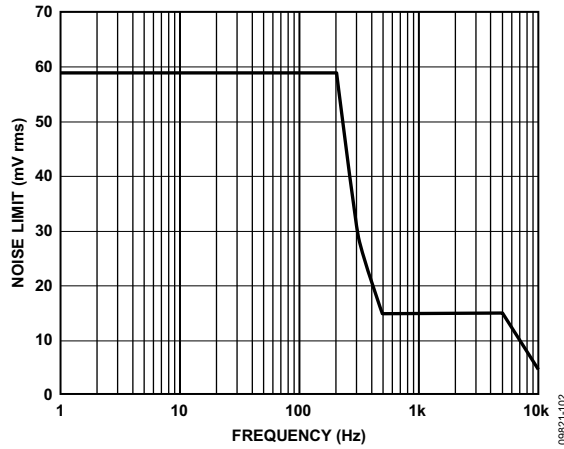


Figure 2. PVDD Maximum Noise Limit

MIPI/DSI SPECIFICATIONS

Unless noted, timing and levels comply with MIPI DPHY standards.

Table 2. DSI High Speed (HS) Specifications

Parameters	Symbol	Temp	Test Level	ADV7533			Unit
				Min	Typ	Max	
DC SPECIFICATIONS							
DSI Input Common Mode Voltage	V_{CMRX}	25°C	VII	70		330	mV
DSI Input High Threshold	V_{IDTH}	25°C	VII			70	mV
DSI Input Low Threshold	V_{IDTL}	25°C	VII	-70			mV
DSI Single-Ended Input High Voltage	V_{IHHS}	25°C	VII			460	mV
DSI Single-Ended Input Low Voltage	V_{ILHS}	25°C	VII	-40			mV
DSI Single-Ended Threshold for Termination Enable	$V_{TERM-EN}$	25°C	VII			450	mV
Differential Input Impedance	Z_{ID}	25°C	VII	80	100	125	Ω
AC SPECIFICATIONS							
Single Channel Data Rate		25°C	IV	200		800	Mbps
Data to Clock Setup Time	t_{SETUP}	25°C	VII	0.15			U_{INST}
Data to Clock Hold Time	t_{HOLD}	25°C	VII	0.15			U_{INST}
DSI Clock Duty Cycle		25°C	VII	45	50	55	%
Common-Mode Interference Beyond 450 MHz	$\Delta V_{CMRX(HF)}$	25°C	VII			100	mV
Common-Mode Interference 50 MHz to 450 MHz	$\Delta V_{CMRX(LF)}$	25°C	VII	-50		+50	mV
Common-Mode Termination	C_{CM}	25°C	VII			60	pF

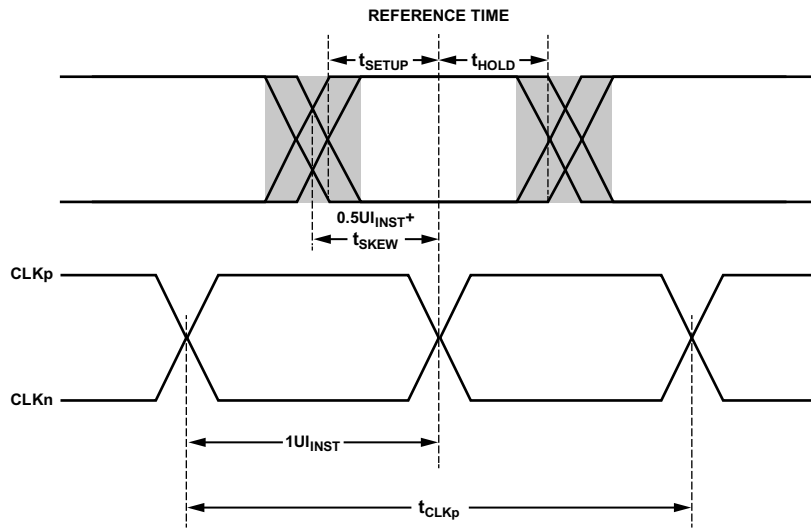


Figure 3. DSI Data to Clock Timing Definitions

Table 3. DSI Low Power Specifications

Parameter	Symbol	Temp	Test Level	Min	Typ	Max	Unit
DC SPECIFICATIONS							
Logic 1 Input Voltage	V_{IH}	25°C	VII	880			mV
Logic 0 Input Voltage, Not in ULP State	V_{IL}	25°C	VII			550	mV
Input Hysteresis	V_{HYST}	25°C	VII	25			mV
AC SPECIFICATIONS							
Input Pulse Rejection	E_{SPIKE}	25°C	VII			300	V × ps
Minimum Pulse Width Response	T_{MIN-RX}	25°C	VII	20			ns
Peak Interference Amplitude	V_{INT}	25°C	VII			200	mV
Interference Frequency	f_{INT}	25°C	VII	450			MHz

Table 4. DSI Pin Specifications

Parameter	Conditions	Temp	Test Level	ADV7533			Unit
				Min	Typ	Max	
DC SPECIFICATIONS							
Pin Signal Voltage Range	V_{PIN}	25°C	VII	-50		+1350	mV
Pin Leakage Current	I_{LEAK}	25°C	VII	-10		+10	μA
Ground Shift	V_{GNDSH}	25°C	VII	-50		+50	mV
Transient Pin Voltage Level	$V_{PIN(absmax)}$	25°C	VII	-0.15		+1.45	V
Maximum Transient Time Above V_{PIN} (Max) or Below V_{PIN} (Min)	$T_{VPIN(absmax)}$	25°C	VII			20	ns

ABSOLUTE MAXIMUM RATINGS

Table 5.

Parameter	Rating
Digital Inputs—I ² C (DDCSDA, DDCSCL, SDA, SCL) and HPD	5.5 V to -0.3 V
Digital Inputs—MIPI/DSI	1.8 V
Digital Inputs—Video/Audio Inputs, CEC_IO, CEC_CLK	3.63 V to -0.3 V
Digital Output Current	20 mA
Operating Temperature Range	-10°C to +85°C
Storage Temperature Range	-40°C to +85°C
Maximum Junction Temperature	150°C
Maximum Case Temperature	150°C

Stresses above those listed under Absolute Maximum Ratings may cause permanent damage to the device. This is a stress rating only; functional operation of the device at these or any other conditions above those indicated in the operational section of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

ESD CAUTION

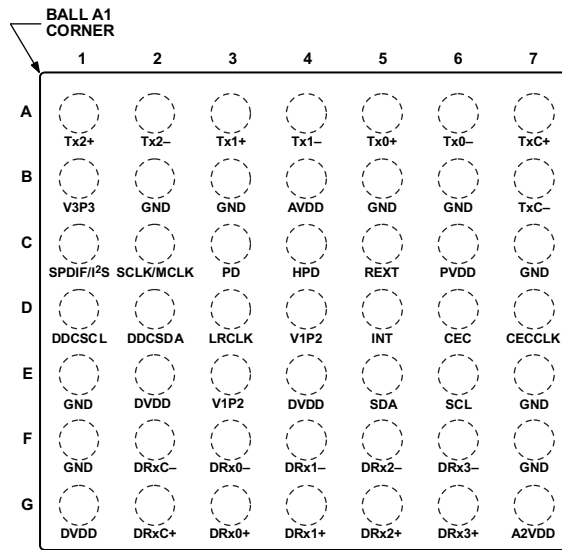


ESD (electrostatic discharge) sensitive device. Charged devices and circuit boards can discharge without detection. Although this product features patented or proprietary protection circuitry, damage may occur on devices subjected to high energy ESD. Therefore, proper ESD precautions should be taken to avoid performance degradation or loss of functionality.

EXPLANATION OF TEST LEVELS

- I 100% production tested.
- II 100% production tested at 25°C and sample tested at specified temperatures.
- III Sample tested only.
- IV Parameter is guaranteed by design and characterization testing.
- V Parameter is a typical value only.
- VI 100% production tested at 25°C; guaranteed by design and characterization testing.
- VII Limits defined by HDMI specification; guaranteed by design and characterization testing.
- VIII Parameter is guaranteed by design.

PIN CONFIGURATION AND FUNCTION DESCRIPTIONS



ADV7533
TOP VIEW
(BALL SIDE DOWN)
Not to Scale

Figure 4. Pin Configuration

Table 6. Pin Function Descriptions

Pin No.	Mnemonic	Type ¹	Description
F6, G6	DRx3-/DRx3+	I	MIPI/DSI Differential Pair for Lane 3. Unused channel should be connected to ground.
F5, G5	DRx2-/DRx2+	I	MIPI/DSI Differential Pair for Lane 2. Unused channel should be connected to ground.
F4, G4	DRx1-/DRx1+	I	MIPI/DSI Differential Pair for Lane 1.
F3, G3	DRx0-/DRx0+	I	MIPI/DSI Differential Pair for Lane 0.
F2, G2	DRxC-/DRxC+	I	MIPI/DSI Differential Clock.
C3	PD	I	Power-Down. Programmable polarity is determined at power-up. The I ² C address and the PD polarity are set by the PD pin state when the supplies are applied to the ADV7533. Internally pulled up for 1; if 0 desired, pull down to ground with a 2 kΩ resistor. Supports typical CMOS logic levels from 1.8 V up to 3.3 V.
C5	R_EXT	I	Sets internal reference currents. Place a 1 kΩ resistor (1% tolerance) between this pin and ground.
C4	HPD	I	Hot Plug Detect Signal. Indicates to the interface whether the receiver is connected. 1.8 V to 5.0 V CMOS logic level.
C1	SPDIF/I ² S	I	S/PDIF or I ² S Audio Data Input. Represents the S/PDIF block or the two channels of audio available through I ² S. Supports typical CMOS logic levels from 1.8 V to 3.3 V.
C2	SCLK/MCLK	I	Audio Clock. Supports typical CMOS logic levels from 1.8 V to 3.3 V. Unused input should be connected to ground.
D3	LRCLK	I	Audio Left/Right Clock Input. Supports typical CMOS logic levels from 1.8 V to 3.3 V. Unused input should be connected to ground.
B7, A7	TxC-/TxC+	O	Differential Clock Output. Differential clock output at pixel clock rate; TMDS logic level.
A2, A1	Tx2-/Tx2+	O	Differential Output Channel 2. Differential output of the red data at 10x the pixel clock rate; TMDS logic level.
A4, A3	Tx1-/Tx1+	O	Differential Output Channel 1. Differential output of the green data at 10x the pixel clock rate; TMDS logic level.
A6, A5	Tx0-/Tx0+	O	Differential Output Channel 0. Differential output of the blue data at 10x the pixel clock rate; TMDS logic level.
D5	INT	O	Interrupt. CMOS logic level. A 2 kΩ pull-up resistor to interrupt the microcontroller I/O supply is recommended. This is a low active signal.
B4	AVDD	P	1.8 V Power Supply for TMDS Outputs. Should be filtered and as quiet as possible.
D4, E3	V1P2	P	Digital Logic Supply (1.2 V or 1.8 V). Set to 1.2 V for lowest power consumption. Should be filtered and as quiet as possible.

Pin No.	Mnemonic	Type ¹	Description
G7	A2VDD	P	1.8 V Power Supply for MIPI/DPHY Input. Should be filtered and as quiet as possible.
E2, E4, G1	DVDD	P	1.8 V Power Supply for Digital and I/O Power Supply. Supply power to the digital logic and I/Os. Should be filtered and as quiet as possible.
C6	PVDD	P	1.8 V Power Supply for the PLL. Should be filtered and as quiet as possible. This supply is the most noise sensitive.
B1	V3P3	P	3.3 V programming pin for HDCP nonvolatile memory.
B2, B3, B5, B6, C7, E1, E7, F1, F7	GND	P	Ground for all domains.
E5	SDA	C	Serial Port Data I/O. Serves as the serial port data I/O slave for register access. Supports CMOS logic levels from 1.8 V to 3.3 V.
E6	SCL	C	Serial Port Data Clock. Serves as the serial port data clock slave for register access. Supports CMOS logic levels from 1.8 V to 3.3 V.
D2	DDCSDA	C	Serial Port Data I/O to Receiver. Serves as the master to the DDC bus. 5 V CMOS logic level.
D1	DDCSCL	C	Serial Port Data Clock to Receiver. Serves as the master clock for the DDC bus. 5 V CMOS logic level.
D6	CEC	I/O	CEC I/O. If unused, pin should be connected to ground.
D7	CEC_CLK	I	CEC External Clock. Can be from 3 MHz to 100 MHz. Settings default to 12 MHz. If unused, pin should be connected to ground.

¹I = input, O = output, P = power supply, C = control.

APPLICATIONS INFORMATION

DESIGN RESOURCES

Analog Devices, Inc., offers the following design resources:

- Evaluation kits
- Reference design schematics
- Hardware and software guides
- Software driver reference code
- HDMI compliance pretest services

Other support documentation is available under the nondisclosure agreement (NDA) from ATV_VideoTx_Apps@analog.com.

Other references include the following:

EIA/CEA-861E, which describes audio and video infoframes as well as the E-EDID structure for HDMI. It is available from the Consumer Electronics Association (CEA).

The HDMI v.1.3, the defining document for HDMI Version 1.3, and the HDMI Compliance Test Specification Version 1.3 are available from HDMI Licensing, LLC.

OUTLINE DIMENSIONS

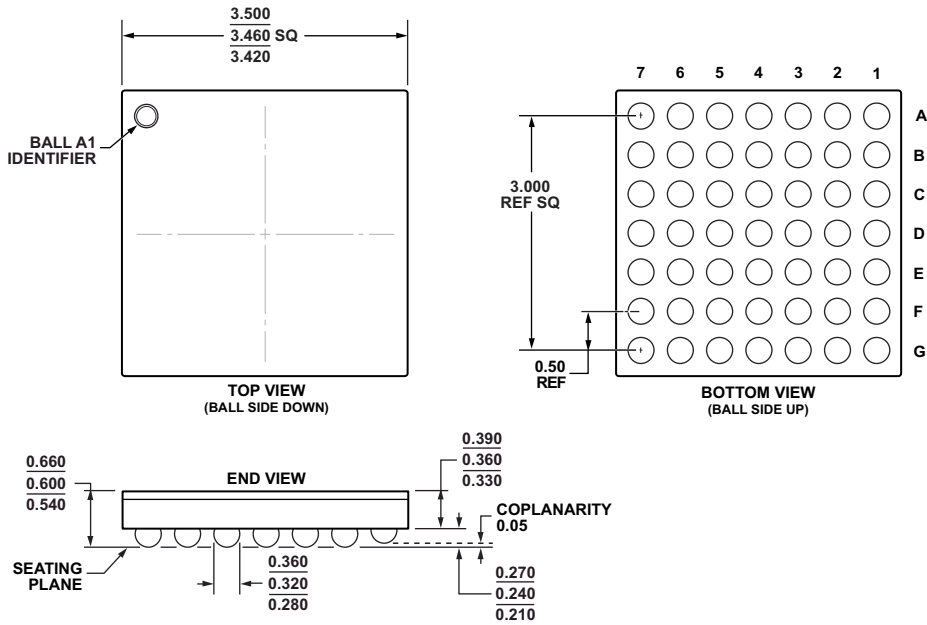


Figure 5. 49-Ball Wafer Level Chip Scale Package [WLCSP]
7 mm x 7 mm Body (CB-49-1)
Dimensions shown in millimeters

08-17-2010-B

ORDERING GUIDE

Model ¹	Temperature Range	Package Description	Package Option
ADV7533BCBZ-RL	-10°C to +85°C	49-Ball Wafer Level Chip Scale Package [WLCSP]	CB-49-1
EVAL-ADV7533-SAZ		Evaluation Board	

¹ Z = RoHS Compliant Part.

¹2C refers to a communications protocol originally developed by Philips Semiconductors (now NXP Semiconductors).

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